Step 250: Preheating semiconductor chip

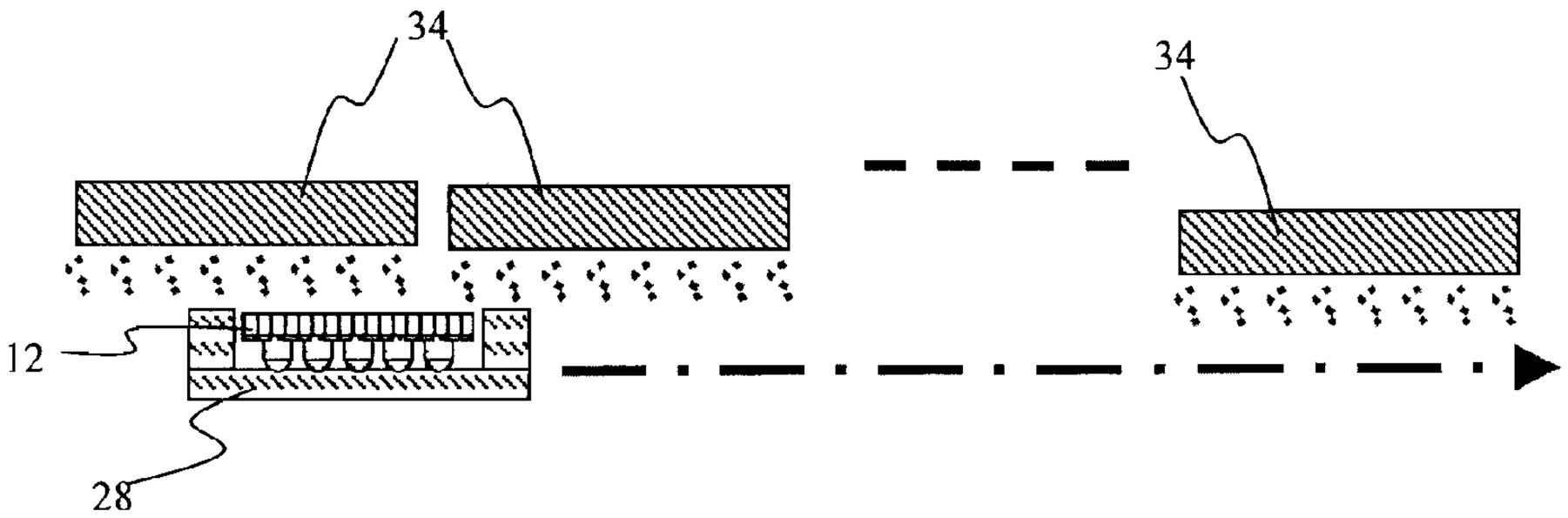


FIG. 3e

Step 260: Picking up of semiconductor chip by bond tool

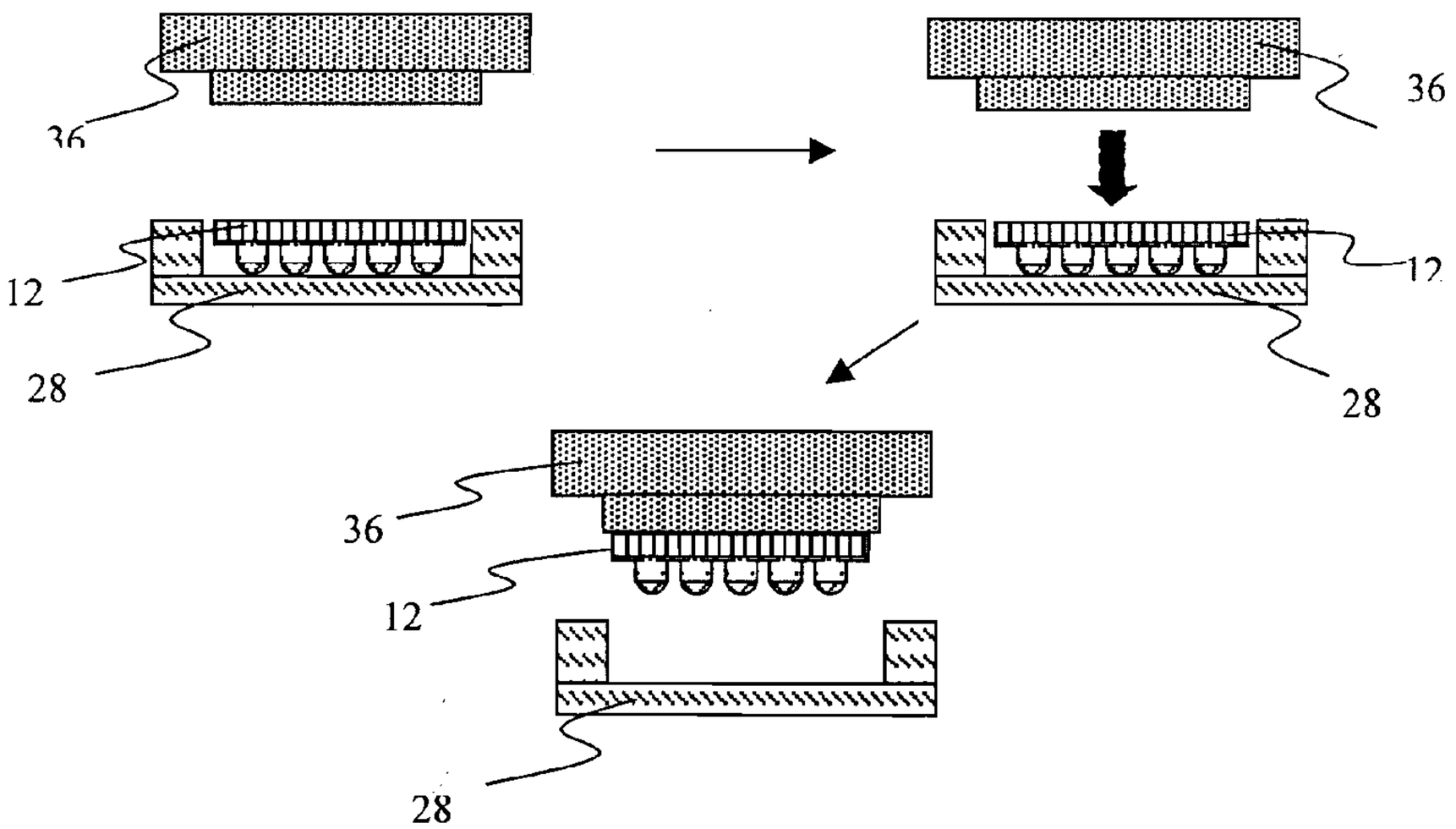


FIG. 3f